

# 30 V, 154 mA, Single, N-Channel, Gate ESD Protection, SC-89

2N7002NT1

### Features

- Low Gate Charge for Fast Switching
- Small 1.6 X 1.6 mm Footprint
- ESD Protected Gate
- **Pb-Free package is available**  
RoHS product for packing code suffix "G"  
Halogen free product for packing code suffix "H"

### Applications

- Power Management Load Switch
- Level Shift
- Portable Applications such as Cell Phones, Media Players, Digital Cameras, PDA's, Video Games, Hand Held Computers, etc.

### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

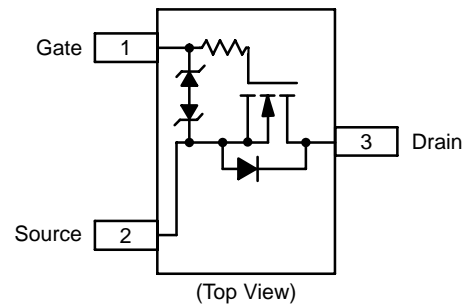
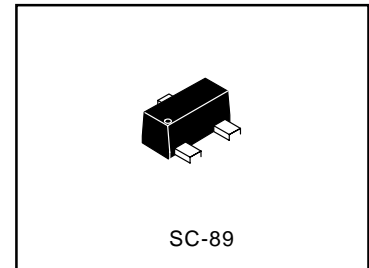
Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	30	V
Gate-to-Source Voltage	V <sub>GS</sub>	±10	V
Continuous Drain Current (Note 1)	I <sub>D</sub>	154	mA
Power Dissipation (Note 1)	P <sub>D</sub>	300	mW
Pulsed Drain Current	I <sub>DM</sub>	618	mA
Operating Junction and Storage Temperature	T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C
Continuous Source Current (Body Diode)	I <sub>SD</sub>	154	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	T <sub>L</sub>	260	°C

### THERMAL RESISTANCE RATINGS

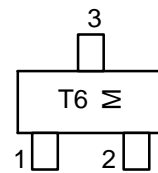
Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 1)	R <sub>θJA</sub>	416	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).



### MARKING DIAGRAM



TF = Specific Device Code  
M = Month Code

### ORDERING INFORMATION

Device	Marking	Shipping
2N7002NT1	T6	3000/Tape&Reel

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = 30\text{ V}$			1.0	$\mu\text{A}$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = 20\text{ V}, T = 85^\circ\text{C}$			1.0	$\mu\text{A}$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 10\text{ V}$			$\pm 25$	$\mu\text{A}$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 5\text{ V}$			$\pm 1.0$	$\mu\text{A}$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 5\text{ V}, T = 85^\circ\text{C}$			$\pm 1.0$	$\mu\text{A}$

**ON CHARACTERISTICS** (Note 2)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_D = 100\ \mu\text{A}$	0.5	1.0	1.5	V
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}, I_D = 154\text{ mA}$		1.4	7.0	$\Omega$
		$V_{GS} = 2.5\text{ V}, I_D = 154\text{ mA}$		2.3	7.5	
Forward Transconductance	$g_{FS}$	$V_{DS} = 3\text{ V}, I_D = 154\text{ mA}$		80		mS

**CAPACITANCES**

Input Capacitance	$C_{ISS}$	$V_{DS} = 5.0\text{ V}, f = 1\text{ MHz}, V_{GS} = 0\text{ V}$		11.5		$\mu\text{F}$
Output Capacitance	$C_{OSS}$			10		
Reverse Transfer Capacitance	$C_{RSS}$			3.5		

**SWITCHING CHARACTERISTICS** (Note 3)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 5.0\text{ V}, I_D = 75\text{ mA}, R_G = 10\ \Omega$		13		ns
Rise Time	$t_r$			15		
Turn-Off Delay Time	$t_{d(OFF)}$			98		
Fall Time	$t_f$			60		

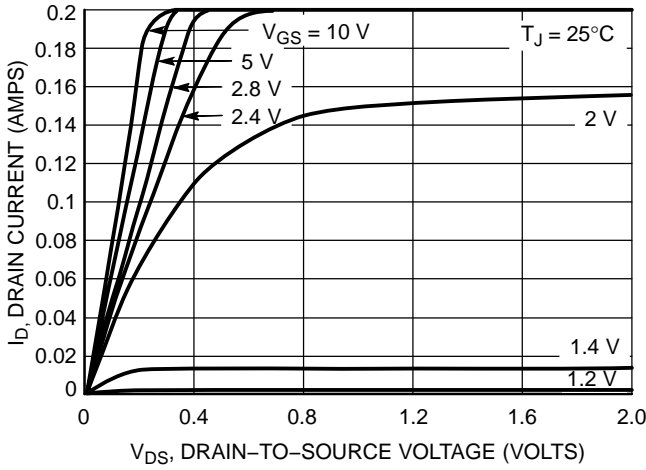
**Drain-Source Diode Characteristics**

Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = 0.154\text{ mA}$		0.77	0.9	V
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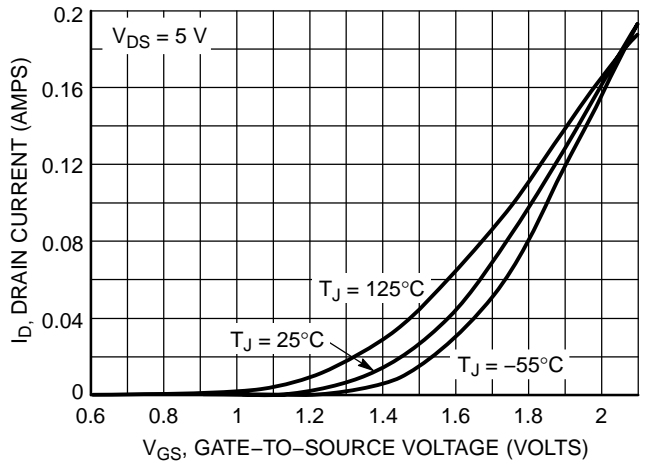
2. Pulse Test: pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .

3. Switching characteristics are independent of operating junction temperatures.

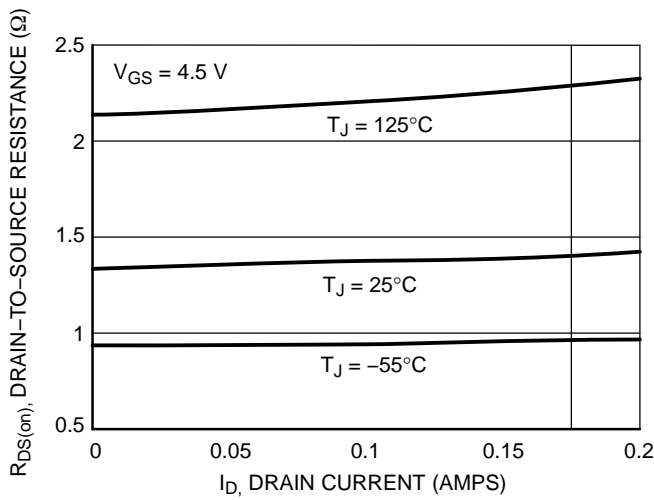
**TYPICAL PERFORMANCE CURVES**



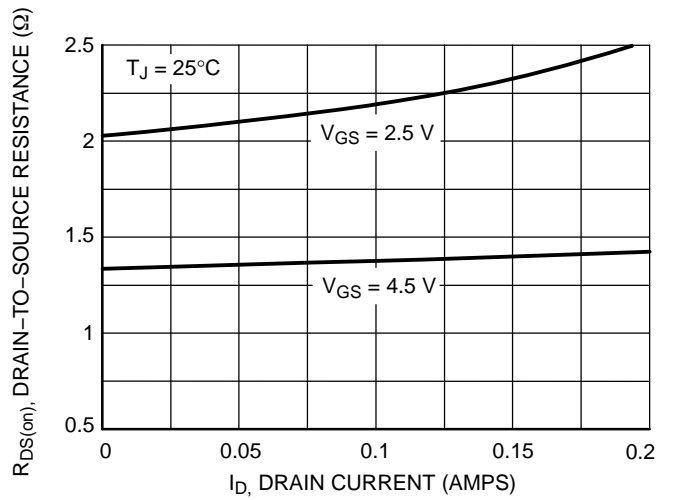
**Figure 1. On-Region Characteristics**



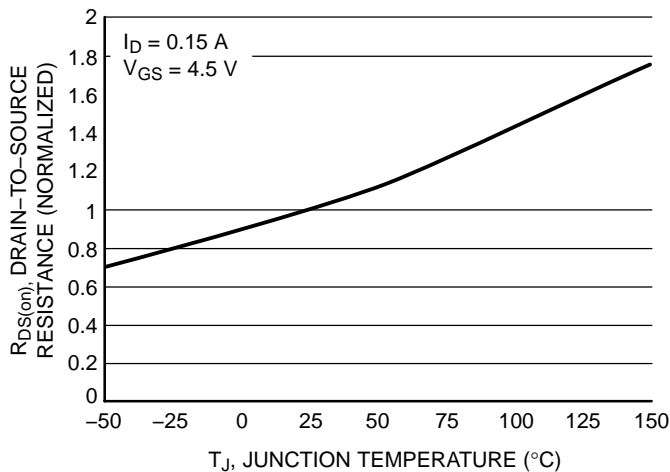
**Figure 2. Transfer Characteristics**



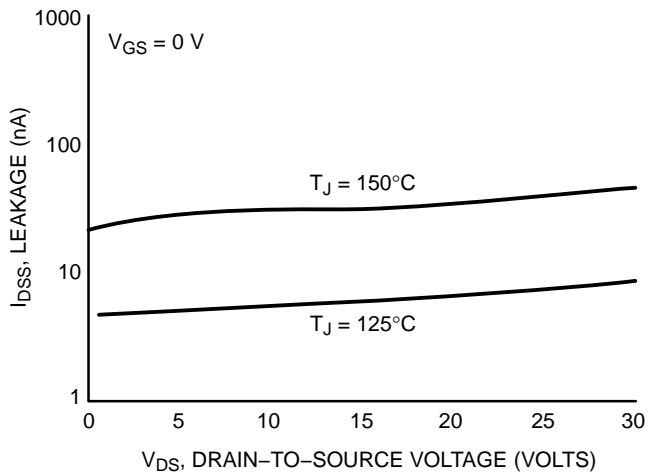
**Figure 3. On-Resistance vs. Drain Current and Temperature**



**Figure 4. On-Resistance vs. Drain Current and Gate Voltage**

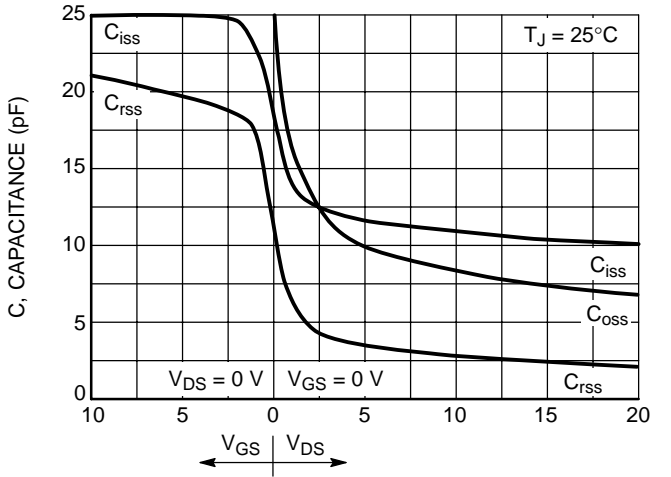


**Figure 5. On-Resistance Variation with Temperature**

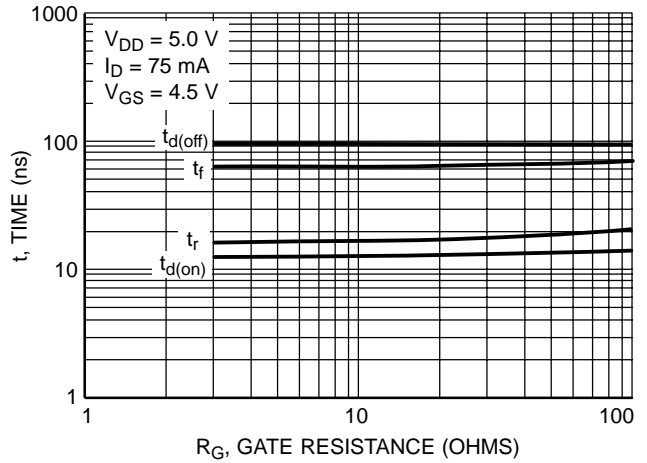


**Figure 6. Drain-to-Source Leakage Current vs. Voltage**

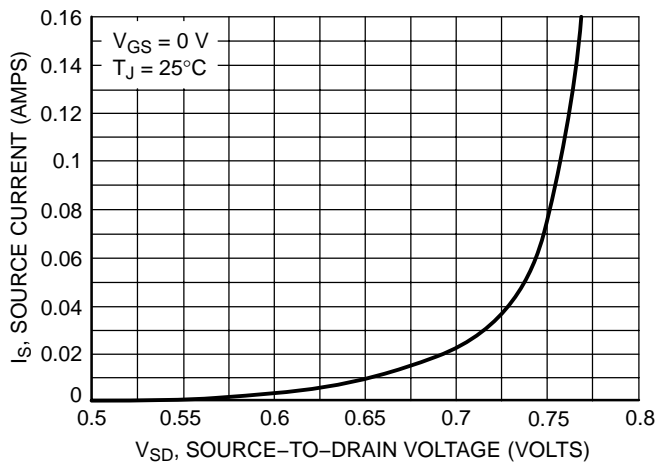
**TYPICAL PERFORMANCE CURVES**



**Figure 7. Capacitance Variation**

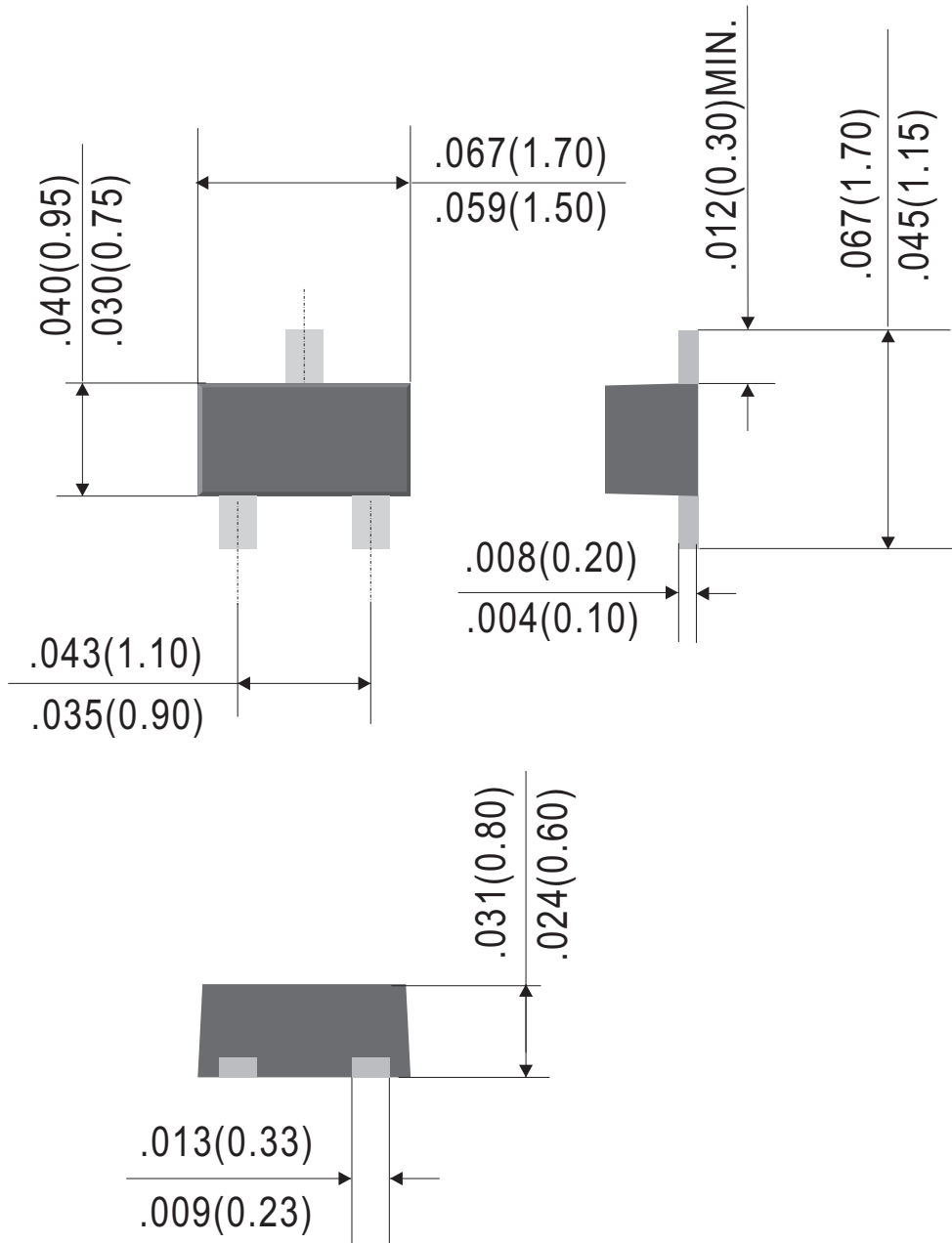


**Figure 8. Resistive Switching Time Variation vs. Gate Resistance**



**Figure 9. Diode Forward Voltage vs. Current**

SC-89



Dimensions in inches and (millimeters)